CLAIMS

1. A thermal print head comprising:

an insulating board;

a glaze layer formed on the board;

a wiring pattern formed on the glaze layer; and

an electrode connected to the wiring pattern,

wherein the electrode includes a pad provided on the wiring pattern and an upper layer formed on the pad, the upper layer having a higher solderability than the pad while having a smaller area than the pad.

2. The thermal print head according to claim 1, wherein the upper layer has a selected dimension which is no greater than 0.75 times a corresponding dimension of the pad.

3. The thermal print head according to claim 1, wherein a joint surface area between the pad and the upper layer is no greater than 0.75^2 times an upper surface area of the pad.

4. The thermal print head according to claim 1, wherein the pad is made of Ag, the upper layer being made of a material selected from the group comprising Ag containing a solderability-improving additive, Ag-Pt and Ag-Pd.

5. The thermal print head according to claim 4, wherein the additive is bismuth oxide.

6. The thermal print head according to claim 1, wherein the pad includes a corner having a contained angle of larger than 90° as viewed in plan for preventing stress concentration.

7. The thermal print head according to claim 1, further comprising a pin contacting the electrode for external connection, the pin being soldered to the upper layer.